

PCN Number:	20190508000	PCN Date:	May 9, 2019
Title:	Datasheet for MCP6291, MCP6292, MCP6294		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



MCP6291, MCP6292, MCP6294

SBOS879C –JULY 2017–REVISED JANUARY 2019

Changes from Revision B (April 2018) to Revision C

Page

• Deleted SOT-23 package preview notation in <i>Device Information</i> table	1
• Added SC70 package to <i>Device Information</i> table.....	1
• Added DCK package information to <i>Device Comparison Table</i>	3
• Deleted DBV package preview notation from <i>Pin Configuration and Functions</i> section.....	4
• Added DCK package drawing and pin functions to <i>Pin Configuration and Functions</i> section.....	4
• Added DBV (SOT-23) and DCK (SC70) thermal information.....	7

Changes from Revision A (October 2017) to Revision B

Page

• Added DGK package to <i>Thermal Information</i> table	8
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The datasheet number will be changing.

Device Family	Change From:	Change To:
MCP6291, MCP6292, MCP6294	SBOS879A	SBOS879C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/MCP6294>

Reason for Change:

To reflect the device pin descriptions accurately.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

MCP6291IDBVR	MCP6291IDCKR	MCP6292IDGKR	MCP6292IDGKT
MCP6292IDR	MCP6294IDR	MCP6294IPWR	MCP6294IPWT

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com